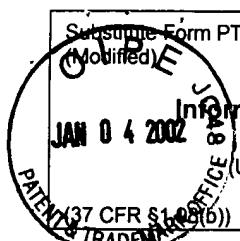


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Sheet 1 of 1

 <p><b>Information Disclosure Statement</b> by Applicant (Use several sheets if necessary)</p>	U.S. Department of Commerce Patent and Trademark Office	Attorney's Docket No. 12816-021001	Application No. 09/898,909
		Applicant Detlef Weber	
		Filing Date July 3, 2001	Group Art Unit 2811

**U.S. Patent Documents**

Examiner Initial	Desig. ID	Patent Number	Issue Date	Patentee	Class	Subclass	Filing Date If Appropriate
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

**Foreign Patent Documents or Published Foreign Patent Applications**

Examiner Initial	Desig. ID	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation	
							Yes	No
PC	AL	EP 0 989 609 A1	03/29/2000	EPO	H01L	23/522		
	AM							
	AN							
	AO							
	AP							

**Other Documents (include Author, Title, Date, and Place of Publication)**

Examiner Initial	Desig. ID	Document
PC	AQ	Rossnagel, S.M., "Filling dual damascene interconnect structures with AlCu and Cu using ionized magnetron deposition", <i>J.Vac. Sci. Technol.</i> , B 13:125-129, (1995)
	AR	
	AS	
	AT	

Examiner Signature

DHAT X. CAO

Date Considered

12/30/02

EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.